

CM8R Hot Air Leveling Tape



CM8R is a high-quality high-temperature resistant tape for printed circuit boards. It is a polyester-reinforced tape coated with a strongly adherent silicone adhesive to withstand the conditions of the hot air leveling process. CM8R distinguishes by its excellent resistance to chemicals and heat.

CM8R is strongly adhering, thermally high resistant and allows for edge-sharp results.

After the hot air leveling process the tape can be removed residue-free.

Application

CM8R is designed in particular for the protection of partial gold or rhodium-coated circuit board areas, multiway connectors or pads.

Technical Specification		
Features	Specification	Tolerance
Overall thickness	0,30 mm (300 µm)	+/- 10%
Tensile force	118 N/100 mm	+/- 10%
Extension	5%	max.
Adhesive force steel	31 N/100 mm	+/- 10%
Temperature	250 °C (5 sec)	
Colour	Rot	

Processing

In compliance with the usual hot air leveling parameters optimal results can be achieved. There are the following processing alternatives:

1. CM8R to be applied to the multiway connectors and pressed via hot roll laminator with about 110°C roller temperature and about 1,5 N/cm² pressing force.
2. CM8R to be applied and pressed via a cold press roller followed by a tempering process for about 20 minutes at a temperature of 70-100°C.
3. CM8R to be applied and pressed via a cold press roller followed by a tempering process in a convection oven for about 20-30 minutes at a temperature of 100°C (120°C / 10-20 minutes, 150°C / 5-10 minutes).

The adhesive tape should be removed soon after the hot air leveling process to prevent residues.

Technical Information

- Width: 19 mm or other dimensions on request
- Roll length: 33 m
- Thickness: 300 µm
- Colour: rot